ABOUT EPTC

The 25th IEEE Electronics Packaging Technology Conference (EPTC2023) is an international event organized by the IEEE RS/EPS/EDS Singapore Chapter and co-sponsored by the IEEE Electronics Packaging Society (EPS). EPTC2023 conference will feature keynotes, technical sessions, technology talks, virtual exhibition corners and networking activities. It aims to provide a platform to cover the technology developments in the complete spectrum of electronics packaging from design to manufacturing. Since its inauguration in 1997, EPTC has been established as a highly reputable international electronics packaging conference and is the IEEE EPS flagship conference in the Asia and Pacific Region 10, covering diverse areas of electronic packaging technology topics. These include modules, components, materials, equipment technology, assembly, reliability, interconnect design, device and systems packaging, heterogeneous integration, wafer-level packaging, flexible electronics, LED, IoT, 5G, emerging technologies, 2.5D/3D integration technology, smart manufacturing, automation, and AI.

The EPTC Technical Program Committee, with more than 100 experts from diverse semiconductor packaging technology areas, is committed to creating an engaging technical program for the international packaging community. The technical program will be supplemented by an exhibition, which provides an opportunity for leading companies to exhibit their latest technologies and products. Last year, 430 attendees from 30 different countries worldwide attended the 24th EPTC conference. This year being our 25th Anniversary, we have a special 4-day program and expect more attendees.

EPTC2023 Organizing Committee would like to invite you to support the sponsorship of this event. A dedicated two-hour sponsors and exhibition session in the Ballroom on Day 2 and Day 3 has been planned, and winners will be picked up through Kahoot game participation for the question submitted by respective sponsors and exhibitors. There is no exhibitor's presentation during the tea break session to enhance exhibitors' and delegates' interaction.

CONFERENCE VENUE INFORMATION

Grand Copthorne Waterfront, Singapore
392 Havelock Road, S169663

For further enquiry, please contact secretariat@eptc-ieee.net or sponsorship@eptc-ieee.net t. We appreciate the consideration of this unique opportunity and look forward to your favourable

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PREMIUM SPONSORSHIPS

1) Platinum Corporate Conference Sponsor (S$ 25,000)

- Most visible among all sponsorships
- Logo listing in the 25th EPTC conference website with an option for linkage to their respective corporate websites
- Displaying of the logo on the conference banners at the conference stage
- Acknowledgement as well as the corporate profile of the sponsor in the Final Conference Program
- Sponsor's logo printed on the conference delegate kit (this could be a Lanyards & bag or equivalent)
- One complimentary premium exhibitor booth (6 panels – 3m* 2m) to showcase the products and services
- Commercial video airtime of 2 min
- Promotional talk time of up to 20 min in the first exhibition session
- Full conference pass (inclusive of professional development courses and Banquet) for 3 pax
- Invitation to attend the VIP dinner for 2 pax
- Conference mobile apps account for networking for 5 pax

2) Gold Corporate Conference Sponsor (S$ 14,000) –

- Logo listing in the 25th EPTC conference website with an option for linkage to their respective corporate websites
- Displaying of the logo on the conference banners at the conference stage
- Acknowledgement and the corporate profile of the sponsor in the final conference digital program
- Sponsor's logo is printed on the conference delegate kit (this could be a Lanyards & bag or equivalent)
- One complimentary standard exhibitor booth (3 panels – 2.25m* 2m) to showcase the products and services
- Commercial video airtime of 1 min
- Promotional talk time of up to 10 min in the first exhibition session
- Full conference pass (inclusive of professional development courses and Banquet) for 2 pax
- Invitation to attend the VIP dinner for 1 pax
- Conference mobile apps account for networking for 3 pax

EPTC 2023 CALL FOR PAPER

Call for papers and detailed conference topics information can be found on EPTC 2023 website.

You are invited to submit abstract(s) on new research and developments in the following packaging categories:

1. Advanced Packaging
2. TSV/Wafer Level Packaging
3. Interconnection Technologies
4. Emerging Technologies
5. Materials and Processing
6. Assembly and Manufacturing Technology
7. Advanced Materials and Process Manufacturing Technology
8. Electrical Simulation & Characterization
9. Mechanical Simulation & Characterization
10. Thermal Characterization & Management
11. Quality, Reliability & Failure Analysis
12. Advanced Optoelectronics and Displays
13. Smart Manufacturing and Packaging Equipment Technology

Important Dates

Online abstract submission start	March 15, 2023
Closing of abstract submission	**May 31, 2023**
Notification of acceptance	June 21, 2023
Full Manuscript Submission	**August 31, 2023**

Please check the eptc website for the latest updates.

REPLY FORM

Yes, (___________________________) wish to participate as:

- **Platinum Corporate Conference Sponsor (S$25,000) -** ☐
- **Gold Corporate Conference Sponsor (S$ 14,000) -** ☐

Company Details:

Contact Person ______________________________ **Title** ______________________

Company ____

Address 1 ____

Address 2 ____

Tel ________________ **Fax** ____________ **Email** ________________

Company Website ____

PAYMENT DUE DATE: August 15, 2023

For further enquiry, please contact secretariat@eptc-ieee.net or sponsorship@eptc-ieee.net

AUTHORISED SIGNATURE: ________________________ *DATE:* ________________________________

*NAME (PRINT):*______________________________*COMPANY STAMP:* ______________________________

FOR OFFICIAL

*ACCEPTED BY EPTC2022 :*_________________________________ *DATE:* ___________________

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